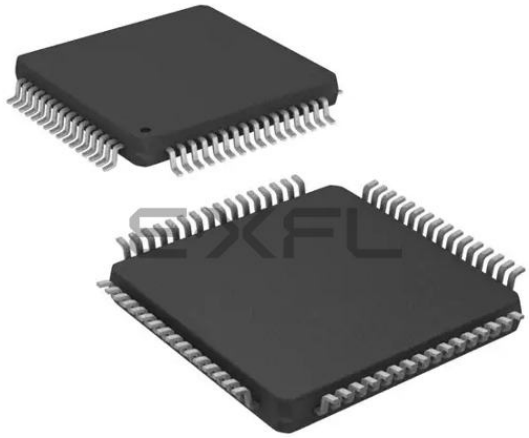
Microchip Technology - PIC32MX575F256HT-80I/PT Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	CANbus, I²C, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx575f256ht-80i-pt

TABLE 7: PIN NAMES FOR 100-PIN USB AND CAN DEVICES (CONTINUED)

100-PIN TQFP (TOP VIEW)

PIC32MX534F064L
PIC32MX564F064L
PIC32MX564F128L
PIC32MX575F512L
PIC32MX575F256L

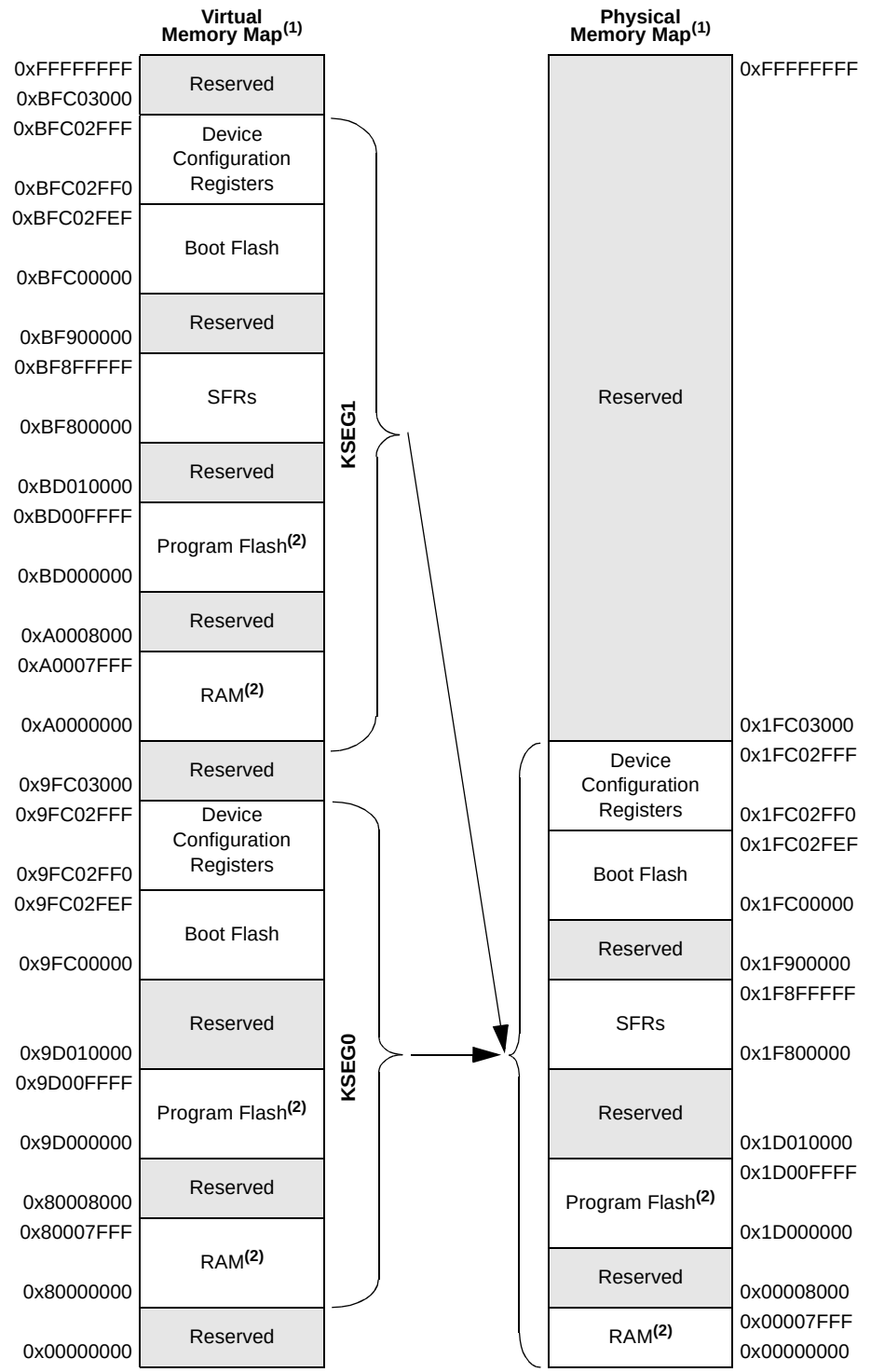
100

1

Pin #	Full Pin Name	Pin #	Full Pin Name
71	IC4/PMCS1/PMA14/RD11	86	VDD
72	SDO1/OC1/INT0/RD0	87	C1RX/PMD11/RF0
73	SOSCI/CN1/RC13	88	C1TX/PMD10/RF1
74	SOSCO/T1CK/CN0/RC14	89	PMD9/RG1
75	VSS	90	PMD8/RG0
76	OC2/RD1	91	TRCLK/RA6
77	OC3/RD2	92	TRD3/RA7
78	OC4/RD3	93	PMD0/RE0
79	IC5/PMD12/RD12	94	PMD1/RE1
80	PMD13/CN19/RD13	95	TRD2/RG14
81	OC5/PMWR/CN13/RD4	96	TRD1/RG12
82	PMRD/CN14/RD5	97	TRD0/RG13
83	PMD14/CN15/RD6	98	PMD2/RE2
84	PMD15/CN16/RD7	99	PMD3/RE3
85	VCAP	100	PMD4/RE4

Note 1: Shaded pins are 5V tolerant.

FIGURE 4-1: MEMORY MAP ON RESET FOR PIC32MX564F064H, PIC32MX564F064L, PIC32MX664F064H AND PIC32MX664F064L DEVICES



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115)) and can be changed by initialization code provided by end user development tools (refer to the specific development tool documentation for information).

7.0 INTERRUPT CONTROLLER

Note: This data sheet summarizes the features of the PIC32MX5XX/6XX/7XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 8. "Interrupts"** (DS60001108) in the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

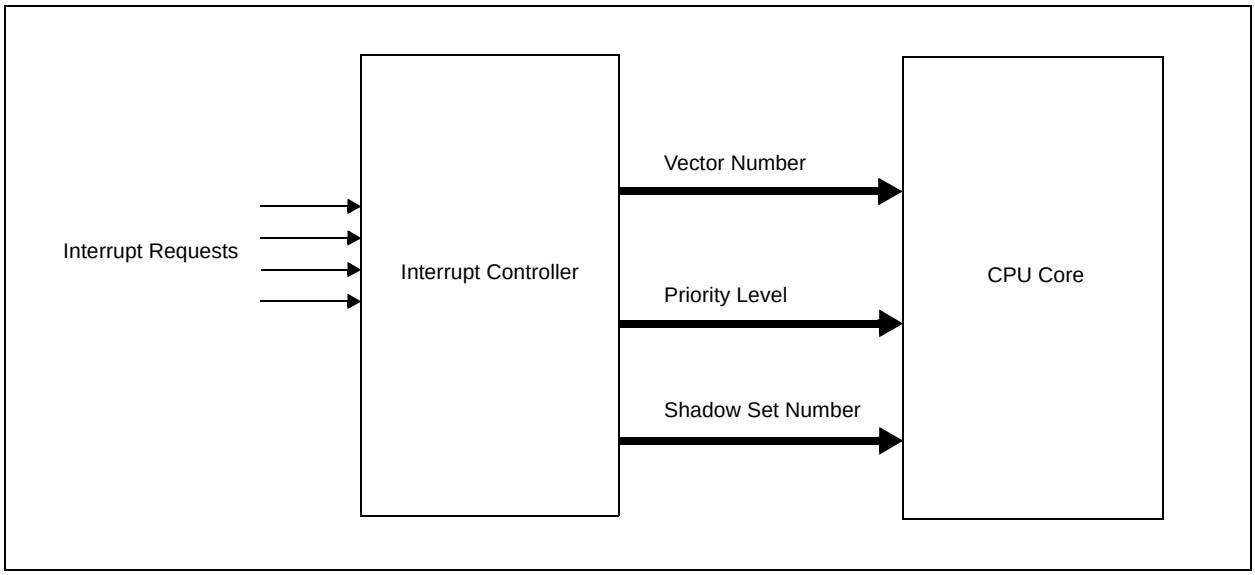
PIC32MX5XX/6XX/7XX devices generate interrupt requests in response to interrupt events from peripheral modules. The interrupt control module exists externally to the CPU logic and prioritizes the interrupt events before presenting them to the CPU.

The Interrupt Controller module includes the following features:

- Up to 96 interrupt sources
- Up to 64 interrupt vectors
- Single and multi-vector mode operations
- Five external interrupts with edge polarity control
- Interrupt proximity timer
- Seven user-selectable priority levels for each vector
- Four user-selectable sub-priority levels within each priority
- Dedicated shadow set for user-selectable priority level
- Software can generate any interrupt
- User-configurable interrupt vector table location
- User-configurable interrupt vector spacing

A simplified block diagram of the Interrupt Controller module is illustrated in Figure 7-1.

FIGURE 7-1: INTERRUPT CONTROLLER MODULE



REGISTER 11-11: U1CON: USB CONTROL REGISTER (CONTINUED)

bit 1 **PPBRST:** Ping-Pong Buffers Reset bit
1 = Reset all Even/Odd buffer pointers to the Even buffer descriptor banks
0 = Even/Odd buffer pointers are not reset

bit 0 **USBEN:** USB Module Enable bit(4)
1 = USB module and supporting circuitry is enabled
0 = USB module and supporting circuitry is disabled

SOFEN: SOF Enable bit(5)
1 = SOF token is sent every 1 ms
0 = SOF token is disabled

Note 1: Software is required to check this bit before issuing another token command to the U1TOK register (see Register 11-15).

2: All host control logic is reset any time that the value of this bit is toggled.

3: Software must set RESUME for 10 ms in Device mode, or for 25 ms in Host mode, and then clear it to enable remote wake-up. In Host mode, the USB module will append a low-speed EOP to the RESUME signaling when this bit is cleared.

4: Device mode.

5: Host mode.

REGISTER 11-18: U1BDTP2: USB BUFFER DESCRIPTOR TABLE PAGE 2 REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	BDTPTRH<23:16>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **BDTPTRH<23:16>:** BDT Base Address bits

This 8-bit value provides address bits 23 through 16 of the BDT base address, which defines the starting location of the BDT in system memory.

The 32-bit BDT base address is 512-byte aligned.

REGISTER 11-19: U1BDTP3: USB BUFFER DESCRIPTOR TABLE PAGE 3 REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	BDTPTRU<31:24>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **BDTPTRU<31:24>:** BDT Base Address bits

This 8-bit value provides address bits 31 through 24 of the BDT base address, defines the starting location of the BDT in system memory.

The 32-bit BDT base address is 512-byte aligned.

REGISTER 21-1: PMCON: PARALLEL PORT CONTROL REGISTER (CONTINUED)

bit 3 **CS1P:** Chip Select 0 Polarity bit(2)
1 = Active-high (PMCS1)
0 = Active-low (PMCS1)

bit 2 **Unimplemented:** Read as '0'

bit 1 **WRSP:** Write Strobe Polarity bit
For Slave Modes and Master mode 2 (PMMODE<9:8> = 00,01,10):
1 = Write strobe active-high (PMWR)
0 = Write strobe active-low (PMWR)
For Master mode 1 (PMMODE<9:8> = 11):
1 = Enable strobe active-high (PMENB)
0 = Enable strobe active-low (PMENB)

bit 0 **RDSP:** Read Strobe Polarity bit
For Slave modes and Master mode 2 (PMMODE<9:8> = 00,01,10):
1 = Read Strobe active-high (PMRD)
0 = Read Strobe active-low (PMRD)
For Master mode 1 (PMMODE<9:8> = 11):
1 = Read/write strobe active-high (PMRD/PMWR)
0 = Read/write strobe active-low (PMRD/PMWR)

Note 1: When using the 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON control bit.

2: These bits have no effect when their corresponding pins are used as address lines.

FIGURE 23-2: ADC CONVERSION CLOCK PERIOD BLOCK DIAGRAM

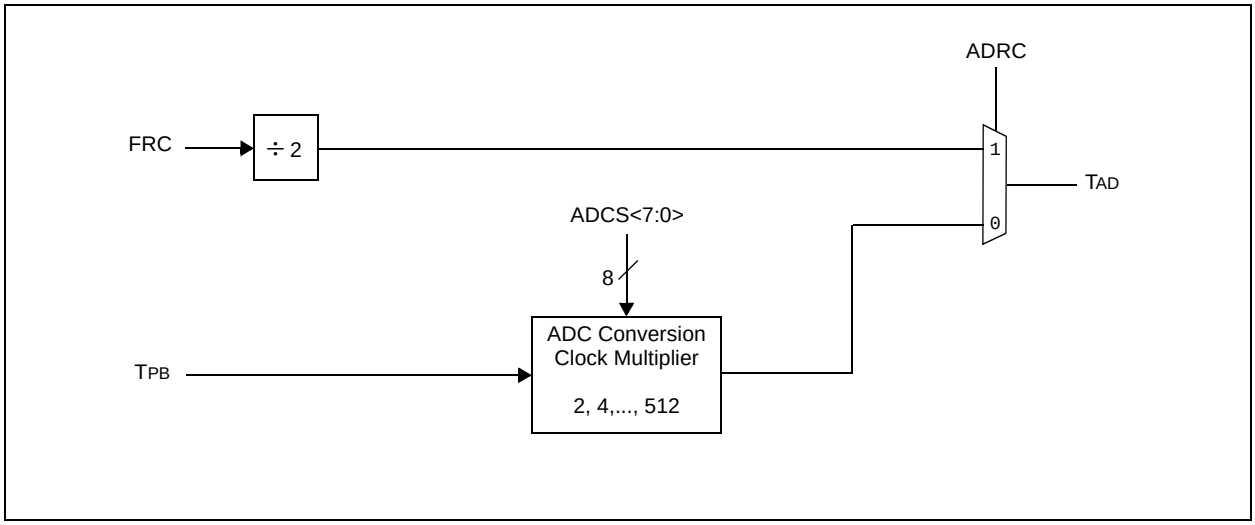


TABLE 24-2: CAN2 REGISTER SUMMARY FOR PIC32MX775F256H, PIC32MX775F512H, PIC32MX795F512H, PIC32MX775F256L, PIC32MX775F512L AND PIC32MX795F512L DEVICES (CONTINUED)

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
C100	C2FLTCON4	31:16	FLTEN19	MSEL19<1:0>		FSEL19<4:0>					FLTEN18	MSEL18<1:0>		FSEL18<4:0>					0000
		15:0	FLTEN17	MSEL17<1:0>		FSEL17<4:0>					FLTEN16	MSEL16<1:0>		FSEL16<4:0:					0000
C110	C2FLTCON5	31:16	FLTEN23	MSEL23<1:0>		FSEL23<4:0>					FLTEN22	MSEL22<1:0>		FSEL22<4:0>					0000
		15:0	FLTEN21	MSEL21<1:0>		FSEL21<4:0>					FLTEN20	MSEL20<1:0>		FSEL20<4:0>					0000
C120	C2FLTCON6	31:16	FLTEN27	MSEL27<1:0>		FSEL27<4:0>					FLTEN26	MSEL26<1:0>		FSEL26<4:0>					0000
		15:0	FLTEN25	MSEL25<1:0>		FSEL25<4:0>					FLTEN24	MSEL24<1:0>		FSEL24<4:0>					0000
C130	C2FLTCON7	31:16	FLTEN31	MSEL31<1:0>		FSEL31<4:0>					FLTEN30	MSEL30<1:0>		FSEL30<4:0>					0000
		15:0	FLTEN29	MSEL29<1:0>		FSEL29<4:0>					FLTEN28	MSEL28<1:0>		FSEL28<4:0>					0000
C140	C2RXFn (n = 0-31)	31:16	SID<10:0>											-—	EXID	—	EID<17:16>		xxxx
		15:0	EID<15:0>																xxxx
C340	C2FIFOBA	31:16	C2FIFOBA<31:0>																0000
		15:0																	0000
C350	C2FIFOCONn (n = 0-31)	31:16	—	—	—	—	—	—	—	—	—	—	—	FSIZE<4:0>					0000
		15:0	—	FRESET	UINC	DONLY	—	—	—	—	TXEN	TXABAT	TXLARB	TXERR	TXREQ	RTREN	TXPRI<1:0>		0000
C360	C2FIFOINTn (n = 0-31)	31:16	—	—	—	—	—	TXNFULLIE	TXHALFIE	TXEMPTYIE	—	—	—	—	RXOVFLIE	RXFULLIE	RXHALFIE	RXN EMPTYIE	0000
		15:0	—	—	—	—	—	TXNFULLIF	TXHALFIF	TXEMPTYIF	—	—	—	—	RXOVFLIF	RXFULLIF	RXHALFIF	RXN EMPTYIF	0000
C370	C2FIFOUAn (n = 0-31)	31:16	C2FIFOUA<31:0>																0000
		15:0																	0000
C380	C2FIFOCIn (n = 0-31)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	C2FIFOCI<4:0>					0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

REGISTER 24-3: CiINT: CAN INTERRUPT REGISTER (CONTINUED)

bit 14 **WAKIF:** CAN Bus Activity Wake-up Interrupt Flag bit
1 = A bus wake-up activity interrupt has occurred
0 = A bus wake-up activity interrupt has not occurred

bit 13 **CERRIF:** CAN Bus Error Interrupt Flag bit
1 = A CAN bus error has occurred
0 = A CAN bus error has not occurred

bit 12 **SERRIF:** System Error Interrupt Flag bit
1 = A system error occurred (typically an illegal address was presented to the system bus)
0 = A system error has not occurred

bit 11 **RBOVIF:** Receive Buffer Overflow Interrupt Flag bit
1 = A receive buffer overflow has occurred
0 = A receive buffer overflow has not occurred

bit 10-4 **Unimplemented:** Read as '0'

bit 3 **MODIF:** CAN Mode Change Interrupt Flag bit
1 = A CAN module mode change has occurred (OPMOD<2:0> has changed to reflect REQOP)
0 = A CAN module mode change has not occurred

bit 2 **CTMRIF:** CAN Timer Overflow Interrupt Flag bit
1 = A CAN timer (CANTMR) overflow has occurred
0 = A CAN timer (CANTMR) overflow has not occurred

bit 1 **RBIF:** Receive Buffer Interrupt Flag bit
1 = A receive buffer interrupt is pending
0 = A receive buffer interrupt is not pending

bit 0 **TBIF:** Transmit Buffer Interrupt Flag bit
1 = A transmit buffer interrupt is pending
0 = A transmit buffer interrupt is not pending

Note 1: This bit can only be cleared by turning the CAN module Off and On by clearing or setting the ON bit (CiCON<15>).

REGISTER 24-4: CiVEC: CAN INTERRUPT CODE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
	—	—	—	FILHIT<4:0>				
7:0	U-0	R-1	R-0	R-0	R-0	R-0	R-0	R-0
	—	ICODE<6:0>(1)						

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-13 **Unimplemented:** Read as '0'

bit 12-8 **FILHIT<4:0>:** Filter Hit Number bit

11111 = Filter 31
11110 = Filter 30
•
•
•
00001 = Filter 1
00000 = Filter 0

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **ICODE<6:0>:** Interrupt Flag Code bits(1)

1111111 = Reserved
•
•
•
1001001 = Reserved
1001000 = Invalid message received (IVRIF)
1000111 = CAN module mode change (MODIF)
1000110 = CAN timestamp timer (CTMRIF)
1000101 = Bus bandwidth error (SERRIF)
1000100 = Address error interrupt (SERRIF)
1000011 = Receive FIFO overflow interrupt (RBOVIF)
1000010 = Wake-up interrupt (WAKIF)
1000001 = Error Interrupt (CERRIF)
1000000 = No interrupt
0111111 = Reserved
•
•
•
0100000 = Reserved
0011111 = FIFO31 Interrupt (CiFSTAT<31> set)
0011110 = FIFO30 Interrupt (CiFSTAT<30> set)
•
•
•
0000001 = FIFO1 Interrupt (CiFSTAT<1> set)
0000000 = FIFO0 Interrupt (CiFSTAT<0> set)

Note 1: These bits are only updated for enabled interrupts.

REGISTER 24-14: CiFLTCON4: CAN FILTER CONTROL REGISTER 4

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	FLTEN19	MSEL19<1:0>		FSEL19<4:0>				
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	FLTEN18	MSEL18<1:0>		FSEL18<4:0>				
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	FLTEN17	MSEL17<1:0>		FSEL17<4:0>				
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	FLTEN16	MSEL16<1:0>		FSEL16<4:0>				

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **FLTEN19:** Filter 19 Enable bit
1 = Filter is enabled
0 = Filter is disabled

bit 30-29 **MSEL19<1:0>:** Filter 19 Mask Select bits
11 = Acceptance Mask 3 selected
10 = Acceptance Mask 2 selected
01 = Acceptance Mask 1 selected
00 = Acceptance Mask 0 selected

bit 28-24 **FSEL19<4:0>:** FIFO Selection bits
11111 = Message matching filter is stored in FIFO buffer 31
11110 = Message matching filter is stored in FIFO buffer 30
•
•
•
00001 = Message matching filter is stored in FIFO buffer 1
00000 = Message matching filter is stored in FIFO buffer 0

bit 23 **FLTEN18:** Filter 18 Enable bit
1 = Filter is enabled
0 = Filter is disabled

bit 22-21 **MSEL18<1:0>:** Filter 18 Mask Select bits
11 = Acceptance Mask 3 selected
10 = Acceptance Mask 2 selected
01 = Acceptance Mask 1 selected
00 = Acceptance Mask 0 selected

bit 20-16 **FSEL18<4:0>:** FIFO Selection bits
11111 = Message matching filter is stored in FIFO buffer 31
11110 = Message matching filter is stored in FIFO buffer 30
•
•
•
00001 = Message matching filter is stored in FIFO buffer 1
00000 = Message matching filter is stored in FIFO buffer 0

Note: The bits in this register can only be modified if the corresponding filter enable (FLTENn) bit is '0'.

REGISTER 24-15: CiFLTCON5: CAN FILTER CONTROL REGISTER 5 (CONTINUED)

bit 15 **FLTEN21:** Filter 21 Enable bit
1 = Filter is enabled
0 = Filter is disabled

bit 14-13 **MSEL21<1:0>:** Filter 21 Mask Select bits
11 = Acceptance Mask 3 selected
10 = Acceptance Mask 2 selected
01 = Acceptance Mask 1 selected
00 = Acceptance Mask 0 selected

bit 12-8 **FSEL21<4:0>:** FIFO Selection bits
11111 = Message matching filter is stored in FIFO buffer 31
11110 = Message matching filter is stored in FIFO buffer 30
•
•
•
00001 = Message matching filter is stored in FIFO buffer 1
00000 = Message matching filter is stored in FIFO buffer 0

bit 7 **FLTEN20:** Filter 20 Enable bit
1 = Filter is enabled
0 = Filter is disabled

bit 6-5 **MSEL20<1:0>:** Filter 20 Mask Select bits
11 = Acceptance Mask 3 selected
10 = Acceptance Mask 2 selected
01 = Acceptance Mask 1 selected
00 = Acceptance Mask 0 selected

bit 4-0 **FSEL20<4:0>:** FIFO Selection bits
11111 = Message matching filter is stored in FIFO buffer 31
11110 = Message matching filter is stored in FIFO buffer 30
•
•
•
00001 = Message matching filter is stored in FIFO buffer 1
00000 = Message matching filter is stored in FIFO buffer 0

Note: The bits in this register can only be modified if the corresponding filter enable (FLTENn) bit is '0'.

REGISTER 25-5: ETHHT0: ETHERNET CONTROLLER HASH TABLE 0 REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	HT<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	HT<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	HT<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	HT<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **HT<31:0>:** Hash Table Bytes 0-3 bits

Note 1: This register is only used for RX operations.
2: The bits in this register may only be changed while the RXEN bit (ETHCON1<8>) = 0 or the HTEN bit (ETHRXFC<15>) = 0.

REGISTER 25-6: ETHHT1: ETHERNET CONTROLLER HASH TABLE 1 REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	HT<63:56>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	HT<55:48>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	HT<47:40>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	HT<39:32>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **HT<63:32>:** Hash Table Bytes 4-7 bits

Note 1: This register is only used for RX operations.
2: The bits in this register may only be changed while the RXEN bit (ETHCON1<8>) = 0 or the HTEN bit (ETHRXFC<15>) = 0.

The processor will exit, or 'wake-up', from Sleep mode on one of the following events:

- On any interrupt from an enabled source that is operating in Sleep mode. The interrupt priority must be greater than the current CPU priority.
- On any form of device Reset
- On a WDT time-out

If the interrupt priority is lower than or equal to the current priority, the CPU will remain Halted, but the PBCLK will start running and the device will enter into Idle mode.

28.3.2 IDLE MODE

In Idle mode, the CPU is Halted but the System Clock (SYSCLK) source is still enabled. This allows peripherals to continue operation when the CPU is Halted. Peripherals can be individually configured to Halt when entering Idle by setting their respective SIDL bit. Latency, when exiting Idle mode, is very low due to the CPU oscillator source remaining active.

Note 1: Changing the PBCLK divider ratio requires recalculation of peripheral timing. For example, assume the UART is configured for 9600 baud with a PB clock ratio of 1:1 and a POSC of 8 MHz. When the PB clock divisor of 1:2 is used, the input frequency to the baud clock is cut in half; therefore, the baud rate is reduced to 1/2 its former value. Due to numeric truncation in calculations (such as the baud rate divisor), the actual baud rate may be a tiny percentage different than expected. For this reason, any timing calculation required for a peripheral should be performed with the new PB clock frequency instead of scaling the previous value based on a change in the PB divisor ratio.

2: Oscillator start-up and PLL lock delays are applied when switching to a clock source that was disabled and that uses a crystal and/or the PLL. For example, assume the clock source is switched from POSC to LPRC just prior to entering Sleep in order to save power. No oscillator start-up delay would be applied when exiting Idle. However, when switching back to POSC, the appropriate PLL and/or oscillator start-up/lock delays would be applied.

The device enters Idle mode when the SLPEN bit (OSCCON<4>) is clear and a `WAIT` instruction is executed.

The processor will wake or exit from Idle mode on the following events:

- On any interrupt event for which the interrupt source is enabled. The priority of the interrupt event must be greater than the current priority of the CPU. If the priority of the interrupt event is lower than or equal to current priority of the CPU, the CPU will remain Halted and the device will remain in Idle mode.
- On any form of device Reset
- On a WDT time-out interrupt

28.3.3 PERIPHERAL BUS SCALING METHOD

Most of the peripherals on the device are clocked using the PBCLK. The Peripheral Bus (PB) can be scaled relative to the SYSCLK to minimize the dynamic power consumed by the peripherals. The PBCLK divisor is controlled by PBDIV<1:0> (OSCCON<20:19>), allowing SYSCLK to PBCLK ratios of 1:1, 1:2, 1:4 and 1:8. All peripherals using PBCLK are affected when the divisor is changed. Peripherals such as USB, interrupt controller, DMA, bus matrix and prefetch cache are clocked directly from SYSCLK. As a result, they are not affected by PBCLK divisor changes.

Changing the PBCLK divisor affects:

- The CPU to peripheral access latency. The CPU has to wait for next PBCLK edge for a read to complete. In 1:8 mode, this results in a latency of one to seven SYSCLKs.
- The power consumption of the peripherals. Power consumption is directly proportional to the frequency at which the peripherals are clocked. The greater the divisor, the lower the power consumed by the peripherals.

To minimize dynamic power, the PB divisor should be chosen to run the peripherals at the lowest frequency that provides acceptable system performance. When selecting a PBCLK divider, peripheral clock requirements, such as baud rate accuracy, should be taken into account. For example, the UART peripheral may not be able to achieve all baud rate values at some PBCLK divider depending on the SYSCLK value.

REGISTER 29-3: DEVCFG2: DEVICE CONFIGURATION WORD 2 (CONTINUED)

bit 2-0 **FPLLIDIV<2:0>:** PLL Input Divider bits
111 = 12x divider
110 = 10x divider
101 = 6x divider
100 = 5x divider
011 = 4x divider
010 = 3x divider
001 = 2x divider
000 = 1x divider

TABLE 32-6: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp			
Parameter No.	**Typical(2)**	**Max.**	**Units**	**Conditions**		
Idle Current (IIDLE)(1,3) for PIC32MX575/675/695/775/795 Family Devices						
DC30	4.5	6.5	mA	-40ºC, +25ºC, +85ºC	—	4 MHz
DC30b	5	7		+105°C		
DC31	13	15	mA	-40ºC, +25ºC, +85ºC	—	25 MHz
DC32	28	30	mA	-40ºC, +25ºC, +85ºC	—	60 MHz
DC33	36	42	mA	-40ºC, +25ºC, +85ºC	—	80 MHz
DC33b	39	45	mA	+105°C		
DC34	—	40	µA	-40°C	2.3V	LPRC (31 kHz)
DC34a		75		+25°C		
DC34b		800		+85°C		
DC34c		1000		+105°C		
DC35	35	—	µA	-40°C	3.3V	
DC35a	65			+25°C		
DC35b	600			+85°C		
DC35c	800			+105°C		
DC36	—	43	µA	-40°C	3.6V	
DC36a		106		+25°C		
DC36b		800		+85°C		
DC36c		1000		+105°C		

Note 1: The test conditions for IIDLE current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Idle mode, program Flash memory Wait states = 111, Program Cache and Prefetch are disabled and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0)
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD
- RTCC and JTAG are disabled

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: This parameter is characterized, but not tested in manufacturing.

4: All parameters are characterized, but only those parameters listed for 4 MHz and 80 MHz are tested at 3.3V in manufacturing.

TABLE 32-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD) (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp			
Param. No.	**Typical(2)**	**Max.**	**Units**	**Conditions**		
Power-Down Current (IPD)(1) for PIC32MX534/564/664/764 Family Devices						
DC40g	12	40	μA	-40°C	2.3V	Base Power-Down Current **(Note 6)**
DC40h	20	120		+25°C		
DC40i	210	600		+85°C		
DC40o	400	1000		+105°C		
DC40j	20	120		+25°C	3.3V	Base Power-Down Current
DC40k	15	80		-40°C	3.6V	Base Power-Down Current
DC40l	20	120		+25°C		
DC40m	113	350(5)		+70°C		
DC40n	220	650		+85°C		
DC40p	500	1000		+105°C		
Module Differential Current for PIC32MX534/564/664/764 Family Devices						
DC41c	—	10	μA	—	2.5V	Watchdog Timer Current: ΔIWDT **(Notes 3,6)**
DC41d	5	—			3.3V	Watchdog Timer Current: ΔIWDT **(Note 3)**
DC41e	—	20			3.6V	Watchdog Timer Current: ΔIWDT **(Note 3)**
DC42c	—	40	μA	—	2.5V	RTCC + Timer1 w/32 kHz Crystal: ΔIRTCC **(Notes 3,6)**
DC42d	23	—			3.3V	RTCC + Timer1 w/32 kHz Crystal: ΔIRTCC **(Note 3)**
DC42e	—	50			3.6V	RTCC + Timer1 w/32 kHz Crystal: ΔIRTCC **(Note 3)**
DC43c	—	1300	μA	—	2.5V	ADC: ΔIADC **(Notes 3,4,6)**
DC43d	1100	—			3.3V	ADC: ΔIADC **(Notes 3,4)**
DC43e	—	1300			3.6V	ADC: ΔIADC **(Notes 3,4)**

Note 1: The test conditions for IPD current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Sleep mode, program Flash memory Wait states = 111, Program Cache and Prefetch are disabled and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0)
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD
- RTCC and JTAG are disabled

2: Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

5: Data is characterized at +70°C and not tested. Parameter is for design guidance only.

6: This parameter is characterized, but not tested in manufacturing.

TABLE 32-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
DI10		I/O Pins:					
		with TTL Buffer	VSS	—	0.15 VDD	V	
		with Schmitt Trigger Buffer	VSS	—	0.2 VDD	V	
DI15		$\overline{MCLR}$(2)	VSS	—	0.2 VDD	V	
DI16		OSC1 (XT mode)	VSS	—	0.2 VDD	V	**(Note 4)**
DI17		OSC1 (HS mode)	VSS	—	0.2 VDD	V	**(Note 4)**
DI18		SDAx, SCLx	VSS	—	0.3 VDD	V	SMBus disabled **(Note 4)**
DI19		SDAx, SCLx	VSS	—	0.8	V	SMBus enabled **(Note 4)**
	VIH	**Input High Voltage**					
DI20		I/O Pins not 5V-tolerant(5)	0.65 VDD	—	VDD	V	**(Note 4,6)**
		I/O Pins 5V-tolerant with PMP(5)	0.25 VDD + 0.8V	—	5.5	V	**(Note 4,6)**
		I/O Pins 5V-tolerant(5)	0.65 VDD	—	5.5	V	
DI28		SDAx, SCLx	0.65 VDD	—	5.5	V	SMBus disabled **(Note 4,6)**
DI29		SDAx, SCLx	2.1	—	5.5	V	SMBus enabled, 2.3V ≤ VPIN ≤ 5.5 **(Note 4,6)**
DI30	ICNPU	**Change Notification Pull-up Current**	—	—	-50	µA	VDD = 3.3V, VPIN = VSS **(Note 3,6)**
DI31	ICNPD	**Change Notification Pull-down Current(4)**	—	50	—	µA	VDD = 3.3V, VPIN = VDD

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: This parameter is characterized, but not tested in manufacturing.

5: See the **"Device Pin Tables"** section for the 5V-tolerant pins.

6: The VIH specification is only in relation to externally applied inputs and not with respect to the user-selectable pull-ups. Externally applied high impedance or open drain input signals utilizing the PIC32 internal pull-ups are guaranteed to be recognized as a logic "high" internally to the PIC32 device, provided that the external load does not exceed the maximum value of ICNPU.

7: VIL source < (VSS - 0.3). Characterized but not tested.

8: VIH source > (VDD + 0.3) for non-5V tolerant pins only.

9: Digital 5V tolerant pins do not have an internal high side diode to VDD, and therefore, cannot tolerate any "positive" input injection current.

10: Injection currents > | 0 | can affect the ADC results by approximately 4 to 6 counts (i.e., VIH Source > (VDD + 0.3) or VIL source < (VSS - 0.3)).

11: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. If **Note 7**, IICL = (((Vss - 0.3) - VIL source) / Rs). If **Note 8**, IICH = ((IICH source - (VDD + 0.3)) / RS). RS = Resistance between input source voltage and device pin. If (VSS - 0.3) ≤ VSOURCE ≤ (VDD + 0.3), injection current = 0.

TABLE 32-9: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DO10	VOL	**Output Low Voltage** I/O Pins: 4x Sink Driver Pins - All I/O output pins not defined as 8x Sink Driver pins	—	—	0.4	V	IOL ≤ 10 mA, VDD = 3.3V
		Output Low Voltage I/O Pins: 8x Sink Driver Pins - RC15	—	—	0.4	V	IOL ≤ 15 mA, VDD = 3.3V
DO20	VOH	**Output High Voltage** I/O Pins: 4x Source Driver Pins - All I/O output pins not defined as 8x Source Driver pins	2.4	—	—	V	IOH ≥ -10 mA, VDD = 3.3V
		Output High Voltage I/O Pins: 8x Source Driver Pins - RC15	2.4	—	—	V	IOH ≥ -15 mA, VDD = 3.3V
DO20A	VOH1	**Output High Voltage** I/O Pins: 4x Source Driver Pins - All I/O output pins not defined as 8x Sink Driver pins	1.5(1)	—	—	V	IOH ≥ -14 mA, VDD = 3.3V
			2.0(1)	—	—		IOH ≥ -12 mA, VDD = 3.3V
			3.0(1)	—	—		IOH ≥ -7 mA, VDD = 3.3V
		Output High Voltage I/O Pins: 8x Source Driver Pins - RC15	1.5(1)	—	—	V	IOH ≥ -22 mA, VDD = 3.3V
			2.0(1)	—	—		IOH ≥ -18 mA, VDD = 3.3V
			3.0(1)	—	—		IOH ≥ -10 mA, VDD = 3.3V

Note 1: Parameters are characterized, but not tested.

2: This driver pin only applies to devices with less than 64 pins.

3: This driver pin only applies to devices with 64 pins.

TABLE 32-10: ELECTRICAL CHARACTERISTICS: BOR

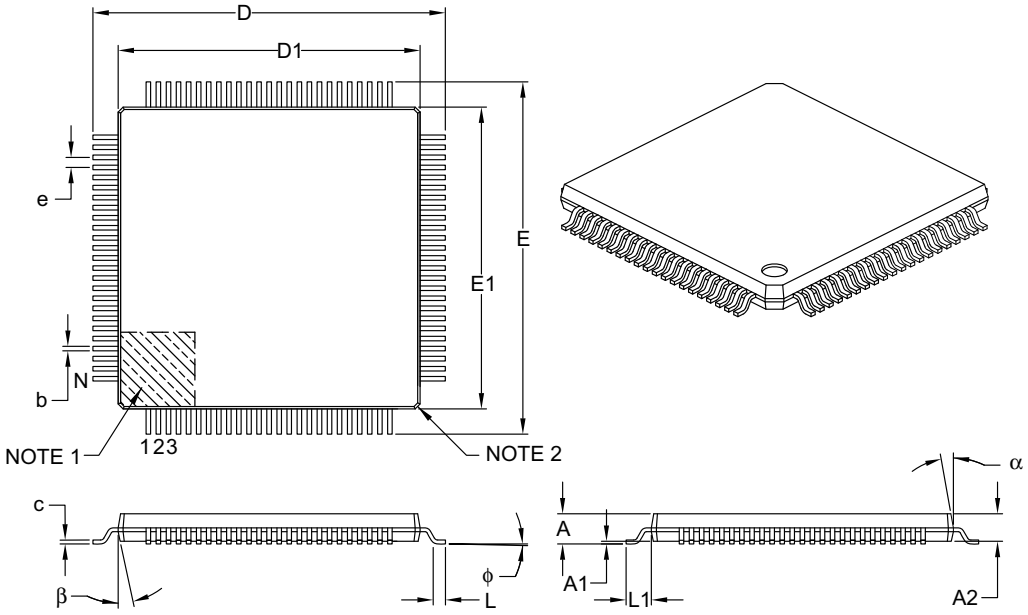
DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.(1)**	**Typical**	**Max.**	**Units**	**Conditions**
BO10	VBOR	BOR Event on VDD transition high-to-low (**Note 2**)	2.0	—	2.3	V	—

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

2: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN.

100-Lead Plastic Thin Quad Flatpack (PT) – 12x12x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		100	
Lead Pitch	e		0.40 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		14.00 BSC	
Overall Length	D		14.00 BSC	
Molded Package Width	E1		12.00 BSC	
Molded Package Length	D1		12.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.13	0.18	0.23
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-100B